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WHAT IS CLAIMED IS:

- 1 1. A wafer for use in a chip device comprising:
- 2 a. a non-passivated wafer;
- 3 b. a first titanium layer;
- 4 c. a first copper layer above the first titanium layer;
- 5 d. a second titanium layer above the first copper layer; and
- 6 e. a second copper layer above the second titanium layer.

- 1 2. A wafer in accordance with claim 1 further comprising a plurality
- 2 of solder bumps.

- 1 3. A chip device comprising a wafer, the wafer comprising:
- 2 a. a non-passivated wafer;
- 3 b. a first titanium layer;
- 4 c. a first copper layer above the first titanium layer;
- 5 d. a second titanium layer above the first copper layer; and
- 6 e. a second copper layer above the second titanium layer.

- 1 4. A method of preparing a wafer for use in a chip device, the method
- 2 comprising:
- 3 providing a non-passivated wafer;
- 4 depositing a first titanium layer on the non-passivated wafer;
- 5 depositing a first copper layer on the first titanium layer;
- 6 depositing a second titanium layer on the first copper layer; and
- 7 depositing a second copper layer on the second titanium layer.

- 1 5. A method of making a bumped wafer, the method comprising:
- 2 providing a non-passivated die;
- 3 alternately sputtering a first titanium layer, a first copper layer, a second
- 4 titanium layer and a second copper layer onto the die;
- 5 depositing photo resist material onto the second copper layer;

6 etching isolation areas thereby removing the photo resist material, the
7 second copper layer, the second titanium layer and the first copper layer at the isolation
8 areas;
9 depositing photo resist material to define bump locations;
10 etching bump locations thereby removing the second copper layer and the
11 second titanium layer at the bump locations
12 depositing under-bump material at the bump locations;
13 depositing solder on the under-bump material;
14 removing the photo resist material
15 etching away the second titanium layer at the isolation locations;
16 etching away the remaining second copper layer; and
17 reflowing the solder.

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